

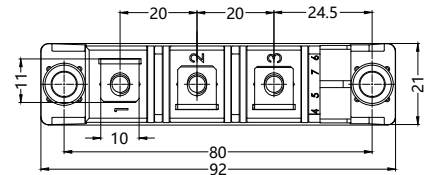
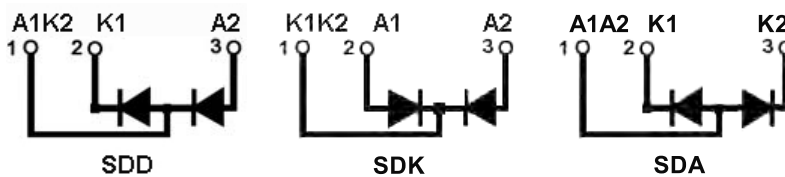
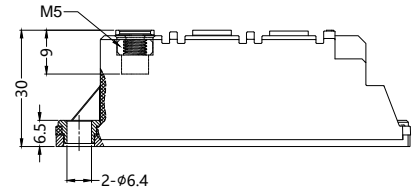
# SDD' \* N18B

## Diode-Diode Modules

Holerance: ±0.5mm  
Dimensions in mm (1mm=0.0394")



Type	V <sub>RSM</sub> V	V <sub>RRM</sub> V
SDDf5 #L * N08B	900	800
SDDf5 #L * N12B	1300	1200
SDDf5 #L * N14B	1500	1400
SDDf5 #L * N16B	1700	1600
SDDf5 #L * N18B	1900	1800



Symbol	Test Conditions	Maximum Ratings	Unit
I <sub>FRMS</sub> I <sub>FAVM</sub>	T <sub>VJ</sub> =T <sub>VJM</sub> T <sub>C</sub> =100°C; 180° sine	$\hat{I}$ $\bar{I}$	A
I <sub>FSM</sub>	T <sub>VJ</sub> =45°C V <sub>R</sub> =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine	$\hat{I}_{50}$ $\hat{I}_{10}$	A
	T <sub>VJ</sub> =T <sub>VJM</sub> V <sub>R</sub> =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	$\hat{I}_{10}$ $\hat{I}_{H0}$	
∫i <sup>2</sup> dt	T <sub>VJ</sub> =45°C V <sub>R</sub> =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine	G <sub>F00</sub> G <sub>00</sub>	A <sup>2</sup> s
	T <sub>VJ</sub> =T <sub>VJM</sub> V <sub>R</sub> =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	F <sub>I 00</sub> F <sub>J€0</sub>	
T <sub>VJ</sub> T <sub>VJM</sub> T <sub>stg</sub>		-40...+150 150 -40...+125	°C
V <sub>ISOL</sub>	50/60Hz, RMS I <sub>ISOL</sub> ≤1mA t=1min t=1s	3000 3600	V~
M <sub>d</sub>	Mounting torque (M5) Terminal connection torque (M5)	2.5-4/22-35 2.5-4/22-35	Nm/lb.in.
Weight	Typ.	105	g

**Sirectifier®**

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## Diode-Diode Modules

Symbol	Test Conditions	Characteristic Values	Unit
$I_R$	$T_{VJ}=T_{VJM}; V_R=V_{RRM}$	10	mA
$V_F$	$I_F=80A; T_{VJ}=25^{\circ}C$	1.38	V
$V_{TO}$	For power-loss calculations only	0.8	V
$r_T$	$T_{VJ}=T_{VJM}$	6.1	m $\Omega$
$Q_S$	$T_{VJ}=125^{\circ}C; I_F=65A; -di/dt=0.6A/us$	50	$\mu C$
$I_{RM}$		6	A
$R_{thJC}$	per diode; DC current per module	1.00 0.50	K/W
$R_{thJK}$	per diode; DC current per module	1.20 0.60	K/W
$d_s$	Creepage distance on surface	12.7	mm
$d_A$	Strike distance through air	9.6	mm
$a$	Maximum allowable acceleration	50	m/s <sup>2</sup>

### FEATURES

- \* International standard package
- \* Copper base plate
- \* Glass passivated chips
- \* Isolation voltage 3600 V~
- \* UL file NO.310749
- \* RoHs compliant

### APPLICATIONS

- \* Supplies for DC power equipment
- \* DC supply for PWM inverter
- \* Field supply for DC motors
- \* Battery DC power supplies

### ADVANTAGES

- \* Space and weight savings
- \* Simple mounting
- \* Improved temperature and power cycling
- \* Reduced protection circuits

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## Diode-Diode Modules

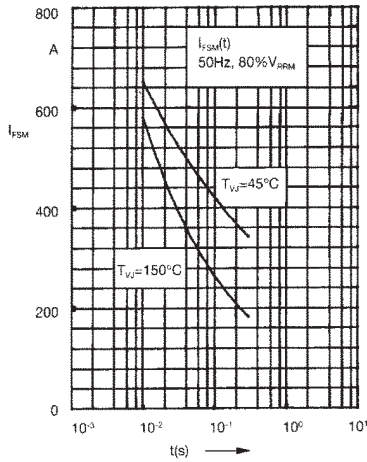


Fig. 1 Surge overload current  
 $I_{FSM}$ : Crest value,  $t$ : duration

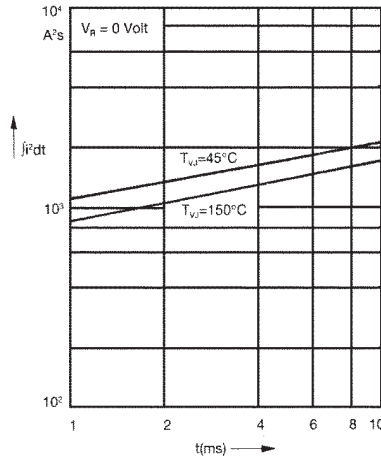


Fig. 2  $\int i^2 dt$  versus time (1-10 ms)

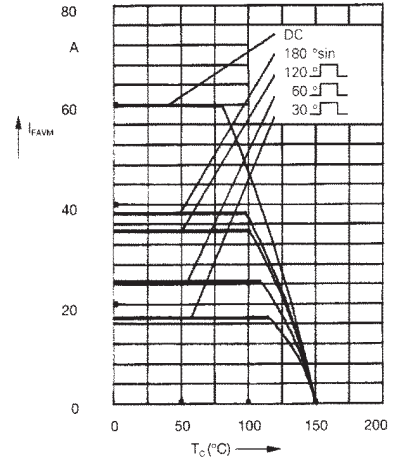


Fig. 2a Maximum forward current at case temperature

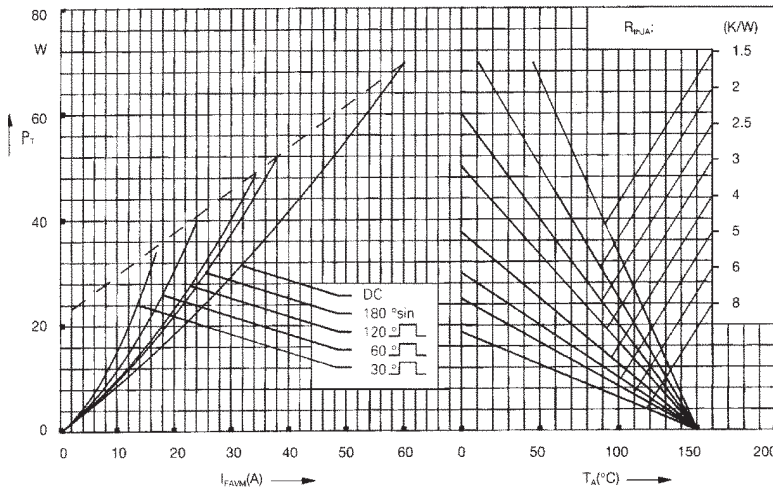


Fig. 3 Power dissipation versus forward current and ambient temperature (per diode)

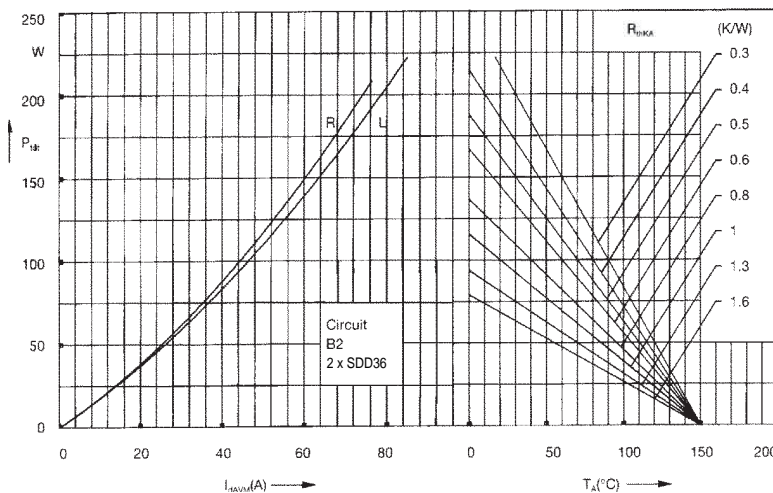


Fig. 4 Single phase rectifier bridge:  
 Power dissipation versus direct output current and ambient temperature  
 R = resistive load  
 L = inductive load

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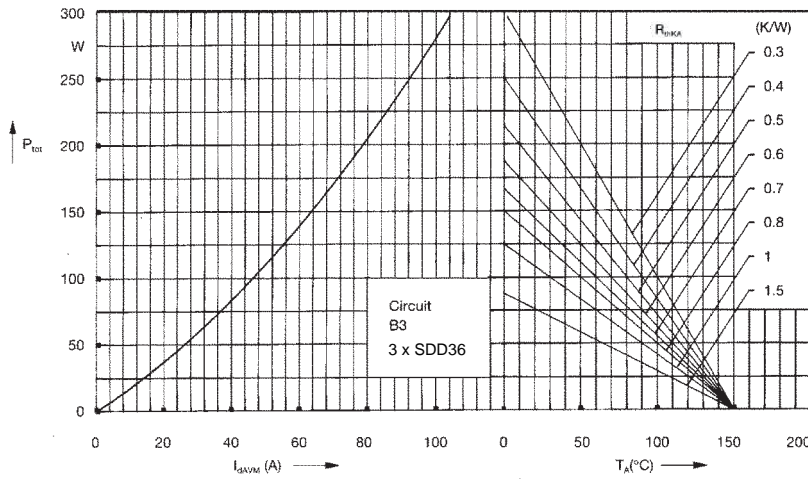


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

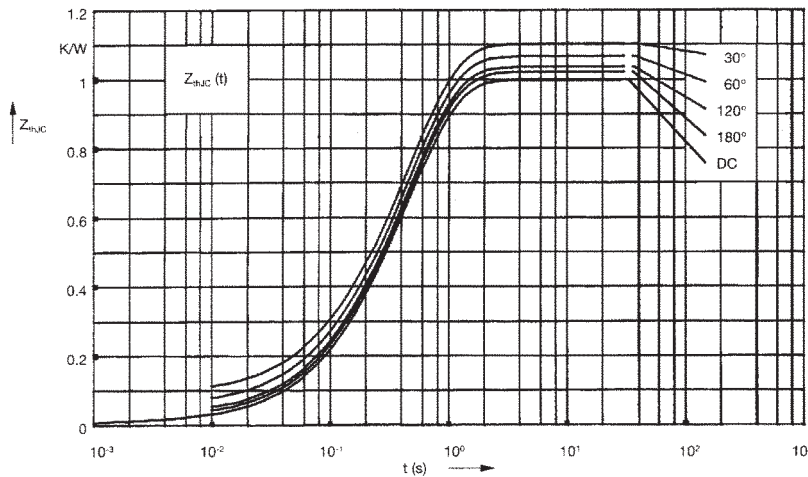


Fig. 6 Transient thermal impedance junction to case (per diode)

$R_{thJC}$  for various conduction angles  $d$ :

$d$	$R_{thJC}$ (K/W)
DC	1.00
180°C	1.02
120°C	1.04
60°C	1.07
30°C	1.10

Constants for  $Z_{thJC}$  calculation:

$i$	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.01	0.0012
2	0.03	0.095
3	0.96	0.455

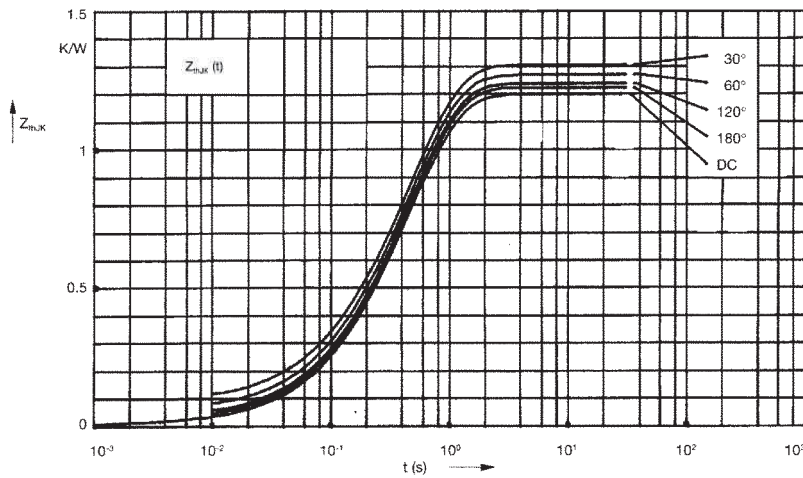


Fig. 7 Transient thermal impedance junction to heatsink (per diode)

$R_{thJK}$  for various conduction angles  $d$ :

$d$	$R_{thJK}$ (K/W)
DC	1.20
180°C	1.22
120°C	1.24
60°C	1.27
30°C	1.30

Constants for  $Z_{thJK}$  calculation:

$i$	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.01	0.0012
2	0.03	0.095
3	0.96	0.455
4	0.2	0.495